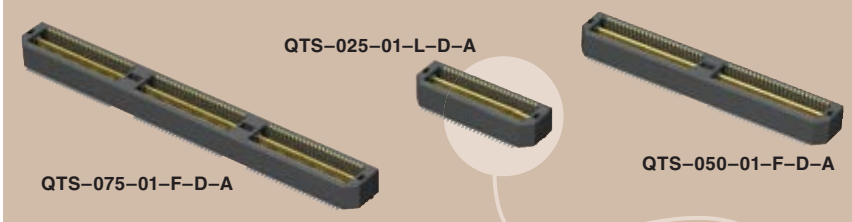
samtec

QSTRIP®

(0,635 mm) .025"

QTS SERIES



HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over 50µ" (1,27 µm) Ni
Current Rating:
Contact: 1.1A per contact @ 30°C Temperature Rise
Ground Plane: 7.8A per ground plane @ 30°C Temperature Rise
Operating Temp:
-55°C to +125°C
Voltage Rating:
285 VAC
Max Cycles:
100
RoHS Compliant:
Yes

Processing:

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0,10 mm) .004" max (025-075)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

- 11 mm & 16 mm stack height (Caution: Some automatic placement/ inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount

Call Samtec.

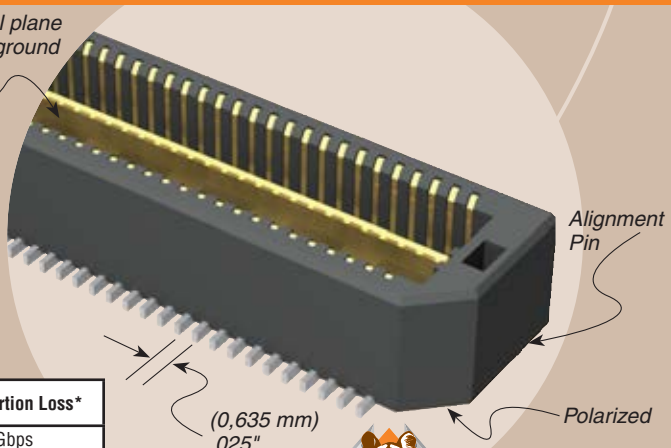
***Note:** –C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QSS

Cable Mates:
SQCD

E.L.P.™ EXTENDED LIFE PRODUCT
10 year Mixed Flowing Gas with 50µ" Gold
Call Samtec for maximum cycles mated with QSS



QTS/QSS 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	–D	9 GHz / 18 Gbps
Differential Pair Signaling	–D	8.5 GHz / 17 Gbps
Differential Pair Signaling	–DP	8.5 GHz / 17 Gbps

*Performance data includes effects of a non-optimized PCB.
Performance data for other stack heights and complete test data available at www.samtec.com?QTS or contact sig@samtec.com

RUGGEDIZED by SAMTEC

ALSO AVAILABLE
- Board spacing standoffs (See SO Series)

QTS	–	NO. OF POSITIONS PER ROW	–	LEAD STYLE	–	PLATING OPTION	–	D	–	A	–	OTHER OPTION

–025, –050, –075
(50 total positions per bank)

Specify LEAD STYLE from chart.

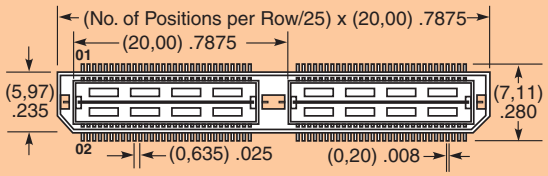
–F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

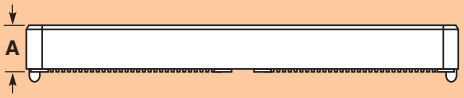
–L
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

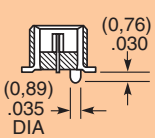
–C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

–K
= (7,00 mm) .275" DIA Polyimide film Pick & Place Pad

–TR
= Tape & Reel







STACK HEIGHTS		
LEAD STYLE	A	MATED HEIGHT
–01	(4,27) .168	(5,00) .197
–02	(7,26) .286	(8,00) .315

Processing conditions will affect mated height.

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